9. (Amended) A method comprising:

forming a trench in a printed circuit board substrate, said trench having a first side surface, a second side surface and a bottom surface;

forming at least one surface on said first side surface, said second side surface and said bottom surface of said trench; and

forming a top surface over said trench having said at least one surface, said top surface being different than said at least one surface.

10. (Amended) The method of claim 9, wherein said at least one surface comprises at least one metalized surface and said top surface comprises a separate top metalized surface.

13. (Amended) The method of claim 11, wherein forming said separate top metalized surface over said trench comprises affixing a bonding surface having a metalized capping surface to said printed circuit board substrate.

14. (Amended) The method of claim 13, wherein said separate top metalized surface on said bonding surface is formed by applying a metal coating on said bonding surface and selectively removing portions of said metal coating such that said separate top metalized surface remains on said bonding surface.

15. (Amended) The method of claim 13, wherein said separate top metalized surface on said bonding surface is formed by providing said bonding surface and selectively aligning said top metalized surface on said bonding surface.

17. (Amended) A method comprising:

forming a trench in a printed circuit board; and

forming a waveguide structure in said trench of said printed circuit board by providing at least one metalized surface along said trench, and bonding a bonding surface having a metalized capping surface to said printed circuit board such that said metalized capping surface is located over said trench having said at least one metalized surface so as to form said waveguide structure.

19. (Amended) The method of claim 18, wherein said waveguide structure comprises said at least one metalized surface on said first sidewall, said second sidewall and said bottom wall and said metalized capping surface on a top of said trench.

Please add new claims 27-34 as follows:

--27. The structure of claim 25, wherein the metalized capping surface is substantially aligned only over the trench.--

--28. The structure of claim 22, wherein the bonding material comprises one of an epoxy and an adhesive.--

--29. The structure of claim 1, wherein applying the bonding surface comprises applying the bonding surface such that the metalized capping surface is substantially aligned only over the trench.--

--30. The method of claim 1, wherein the bonding surface includes a bonding material comprising one of an epoxy and an adhesive.--

-- 31. The method of claim 10, wherein the separate top metalized surface is substantially aligned only over the trench.--

--32. The method of claim 13, wherein the bonding surface includes a bonding material comprising one of an epoxy and an adhesive.--

--33. The method of claim 17, wherein the metalized bonding surface is substantially aligned only over the trench.--

--34. The method of claim 17, wherein the bonding surface includes a bonding material comprising one of an epoxy and an adhesive.--